

EEL3701

Menu

- LSI Components
 - > Random Access Memory (RAM)
 - Static RAM (SRAM)
 - Dynamic RAM (DRAM)
 - Read-Only Memory (ROM)

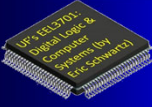




See figures from Lam text on web:
[RAM_ROM_ch6.pdf](#)

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Static Random Access Memory (SRAM)

- It can be thought of as 1 long **vector of registers**. Each register is given the “name” of its ordered index or location. We call this the **address**. Addresses are usually given in HEX.

[Example] 1 k x 8 RAM

of words

000
001
002
⋮
3FD
3FE
3FF

HEX

Location or “Address”

7 0

0
1
2
⋮
1021
1022
1023

Decimal

word size

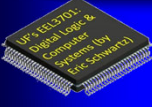
1K = 1024 bytes
= 2^{10} bytes

1 byte = 8 bits

- 8 bits = 1 byte, 4 bits = 1 nibble,
- 1k = 2^{10} = 1024, M = 2^{20} (mega-), G = 2^{30} (giga-), T = 2^{40} (tera-)
- 1k x 8bits = 1KB = 1 kilobyte = 2^{10} bytes

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 **EEL3701** **Static RAM**

- To address $1k = 2^{10}$ bits, we need 10 “address lines” ($A_9 \sim A_0$)
- The data needs 8 lines designated as $D_7 \sim D_0$
- Since any of the $1k$ locations is usable, the address lines $A_9 \sim A_0$ will range from
 $00\ 0000\ 0000B$ to $11\ 1111\ 1111B$
 $(0\ 0\ 0H)$ to $(3\ F\ FH)$

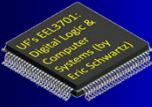
 **Postfix Abbr:** H = Hexadecimal, B = Binary, O = Octal, and D = Decimal

- Any RAM chip will have n-address lines, m-data lines, and a “few” control lines.
- For RAM, “control” is usually a CE or CS (Chip Enable or Chip Select), a WE (Write Enable), a RD (Read) or OE (Output enable), *etc.*
- The data lines are usually bi-directional (time-multiplexed).
- To “save” pins, WE may indicate the direction of data travel.

Prefix Abbr: \$ = Hexadecimal, % = Binary, @ = Octal

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 **EEL3701** **(Static) RAM Model**

- RAM's are said to be “**volatile**,” i.e., information remains while power is “on.”
- Typical access times for SRAM are $10 \sim 100ns$ in CMOS types. Faster (less capacity in bytes) IC technology (TTL, *etc.*) are also available.
- A “typical” $1k \times 8$ RAM looks like this $\rightarrow$
- If no OE or OE=1, then
 > If WE=0, read; if 1, write

RAM Timing – See next page

RAM Model Diagram:

The diagram shows a RAM block with the following connections:

- Address Bus:** n lines, labeled $A_{n-1} \sim A_0$.
- Data Bus:** m lines, labeled $D_{m-1} \sim D_0$.
- Control Bus:** Lines for CS/CE, WE, and OE.

RAM Pinout:

- 10 lines for $A_9 \sim A_0$
- 8 lines for $D_7 \sim D_0$
- CS/CE
- WE
- OE

Operation Table:

Operation	CE	WE	OE	D
Disable	0	-	-	Hi-Z
Disable	1	0	0	Hi-Z
Read	1	0	1	Out
Write	1	1	-	In

2114A: $1k \times 4$ SRAM
Access time: $\sim 100\ ns$
Address range: 0 - \$3FF

32kx8 SRAM
Access time: from 7ns to 100ns
Address range: 0 - \$7FFF

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EEL3701 Simplified SRAM

- Sometimes block diagrams for SRAM are simplified, removing OE(L).
 - > Since WE(L) has higher priority than OE(L), OE(L) can be always true, i.e., GND.
 - > In this case, if WE is true, writing to SRAM; otherwise reading.

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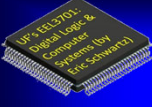
EEL3701 SRAM Timing Diagrams

- Since no OE, the WE determines read or write cycles

Ref: Lam Fig 6.26

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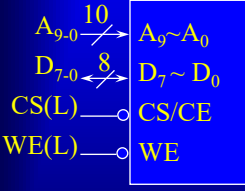
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 **EEL3701**

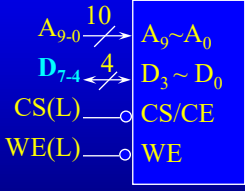
RAM Expansion

- Make a 1k x 8 RAM from 1k x 4 RAMs

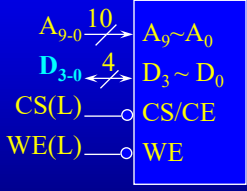
1k x 8 RAM



1k x 4 RAM



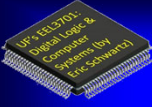
1k x 4 RAM



- Since no OE, the WE determines read or write cycles

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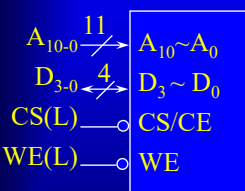
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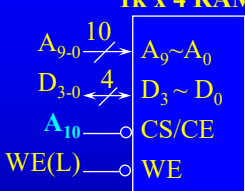
RAM Expansion

- Make a 2k x 4 RAM from two 1k x 4 RAMs

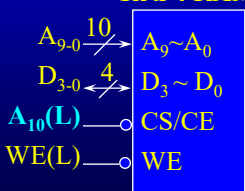
2k x 4 RAM



1k x 4 RAM



1k x 4 RAM



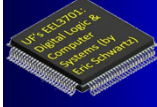


Can you make a 2k x 8 SRAM with only 1k x 4 SRAMs?

- Since no OE, the WE determines read or write cycles

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RAM connected to Microprocessor

- Example RAM 1: Add a 4-byte x 8 RAM module to a hypothetical μP with 3 address pins, 8 data pins and control pins R, W and E

μP
 A_2-A_0
 D_7-D_0
 R
 W
 E

1st Byte
 A_1-A_0
 D_7-D_0
 RAM
 OE
 WE
 CS

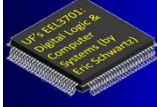
54_{16}
 $F7_{16}$
 39_{16}
 $B8_{16}$
 Last Byte

- D_7-D_0 on the μP connect to D_7-D_0 on the RAM
- $OE = E \bullet R$
- $WE = E \bullet W$
- Two of the three address lines go to A_1-A_0 on the RAM; $CS =$ unused one

1. $CS=A_2$; $A_1=A_1$; $A_0=A_0$
2. $CS=A_1$; $A_1=A_2$; $A_0=A_0$
3. $CS=A_0$; $A_1=A_2$; $A_0=A_1$
4. $CS=/A_2$; $A_1=A_1$; $A_0=A_0$

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RAM to implement Equations

- The behavior of the RAM can be thought of as if it were a 3-input 8 output device (e.g., using **Choice 4**)

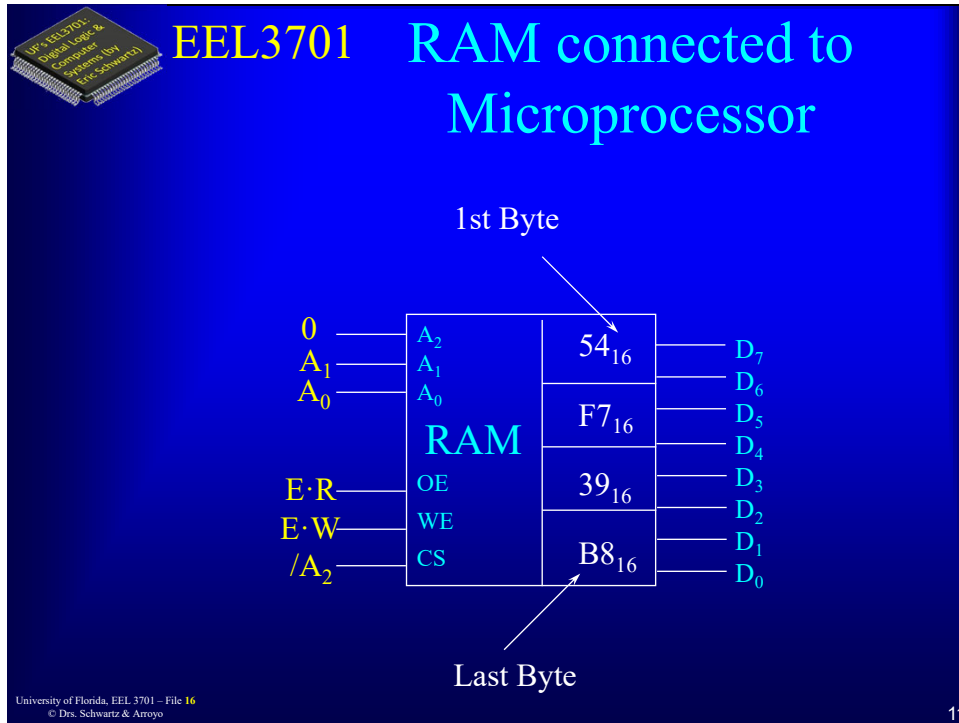
A_2	A_1	A_0	D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	
0	0	0	0	1	0	1	0	1	0	0	$= 54_{16}$
0	0	1	1	1	1	1	0	1	1	1	$= F7_{16}$
0	1	0	0	0	1	1	1	0	0	1	$= 39_{16}$
0	1	1	1	0	1	1	1	0	0	0	$= B8_{16}$

For example: $D_5 = /A_2 \cdot (A_1 + A_0)$
 $D_4 = /A_2 \cdot 1$
 $D_1 = /A_2 \cdot /A_1 \cdot A_0$

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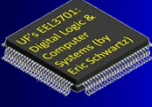
EEL3701 RAM connected to μP

- What are the consequences of these choices?
 - >Choice 1: CS=A₂; A₁=A₁; A₀=A₀
 - When the mP issues address 000; the RAM does not respond since CS=A₂=0; similarly for addresses 001, 010, 011
 - For address 100 the mP reads \$54, for 101 the mP reads \$F7, for 110 the mP reads \$39, for 111 the mP reads \$B8
 - The 4-byte RAM starts at address 100

Address	Choice 1	Choice 2	Choice 3	Choice 4
0 0 0	None	None	None	\$54
0 0 1	None	None	\$54	\$F7
0 1 0	None	\$54	None	\$39
0 1 1	None	\$F7	\$F7	\$B8
1 0 0	\$54	None	None	None
1 0 1	\$F7	None	\$39	None
1 1 0	\$39	\$39	None	None
1 1 1	\$B8	\$B8	\$F8	None

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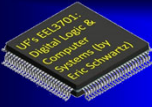


EEL3701 Conclusions from Example RAM 1

- The data in the RAM will not be accessed contiguously unless we connect the matching contiguous low order lines to the RAM $\therefore A_1=A_1$ and $A_0=A_0$
- We have a choice of $CS=/A_2$ or $CS=A_2$; if we want the RAM in the “low memory range” choose $CS=/A_2$; if in the “high memory range” $CS=A_2$
- For contiguous access we always connect the low order address pins to **all** the RAM address pins
- $CS = f(\text{unused high order address lines})$. If we have m unused address lines we will have 2^m starting addresses for the contiguous memory block

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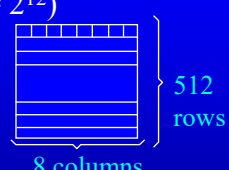
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EEL3701 Data Arrangement in RAM

Sometimes the RAM is organized internally as a “**matrix**” with a column address & a row address, e.g., 8 x 512 x 8 bit RAM
 $\therefore (8 \times 512) \times 8 = 4k \times 8$ RAM, but we use 9 bits as a row address and 3 bits for a column address. ($512 = 2^9$, $8 = 2^3$, $4k = 2^{12}$)
 Total Storage = 2^{12} words (word=8 bits)

or 000 0 0000 0000
 to 111 1 1111 1111
 or \$000 (=000H) to \$FFF (=FFFH)

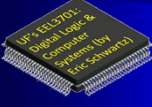


We can think of lines $A_{11} \sim A_9$ as “**column selector**” and lines $A_8 \sim A_0$ as a “**row selector**.” Each selected element is eight bits deep.

The user does not really care how the RAM is organized. He only “sees” the fact that it stores $4k \times 8$.

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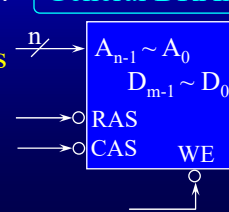


EEL3701 Dynamic RAM (DRAM)

- DRAM is also “volatile” RAM
- DRAM must be periodically rewritten (refreshed) else the info will be lost!
 - DRAM’s have higher density (more bits per unit area of silicon) and are “faster” (but since we have to refresh them, the “net” time may be slower than SRAM).
 - Can get 16M x 8 bits (16M= 4k x 4k = 2^{24}) and larger.
- For the details of “refreshing” and timing involve using lines RAS & CAS, see next slide.

General DRAM Model

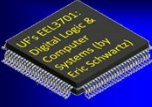
• n-bits for row Address Bus $\xrightarrow{n}$ $A_{n-1} \sim A_0$
 • n-bits for column $D_{m-1} \sim D_0$ $\xleftarrow{m}$ Data Bus
 • $\Rightarrow 2*n$ address bits



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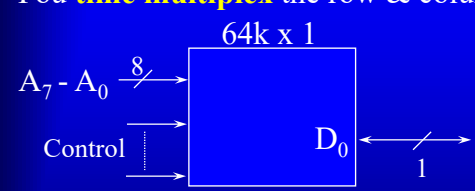
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EEL3701 DRAM Memory Organization

- A typical 64k x 1bit DRAM is organized so that one supplies the 16-bit address as an 8-bit row & 8-bit column using **the same input pins**. You **time multiplex** the row & column address info.

$64k = 2^{16} = (2^8) (2^8)$

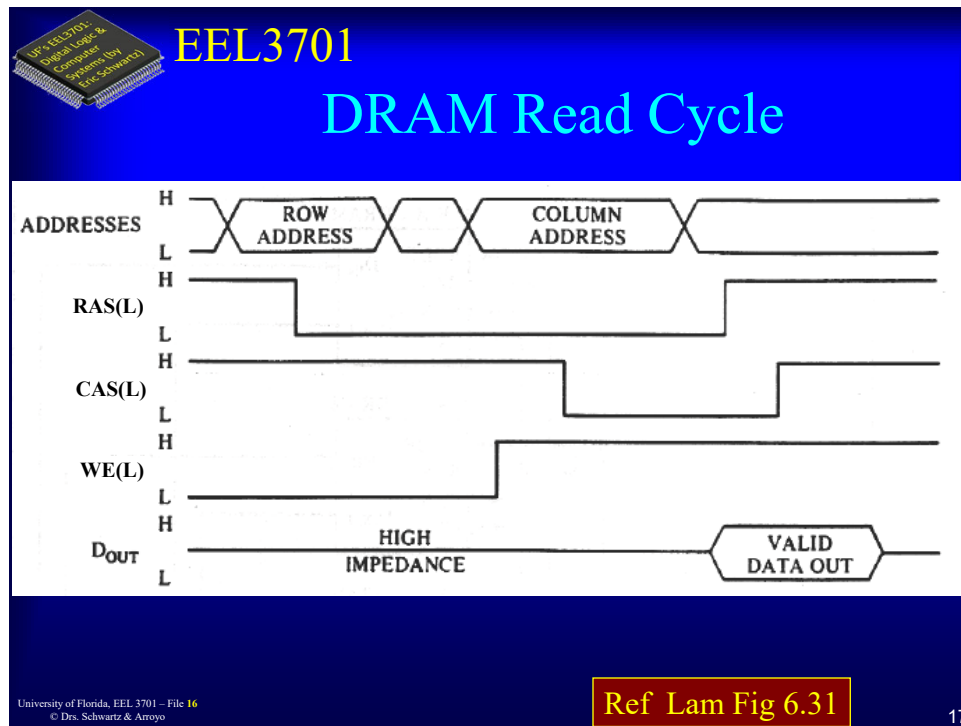


First you supply the high order 8 bits (row address), **then** the low order 8 bits (column address)
- To interface this type IC, the digital designer must design a sequential circuit to receive the 16 bit address as a parallel input and feed it as 2 8-bit numbers to the DRAM. This is called a **DRAM controller**.
- See timing diagram of a typical DRAM in on **next pages**.

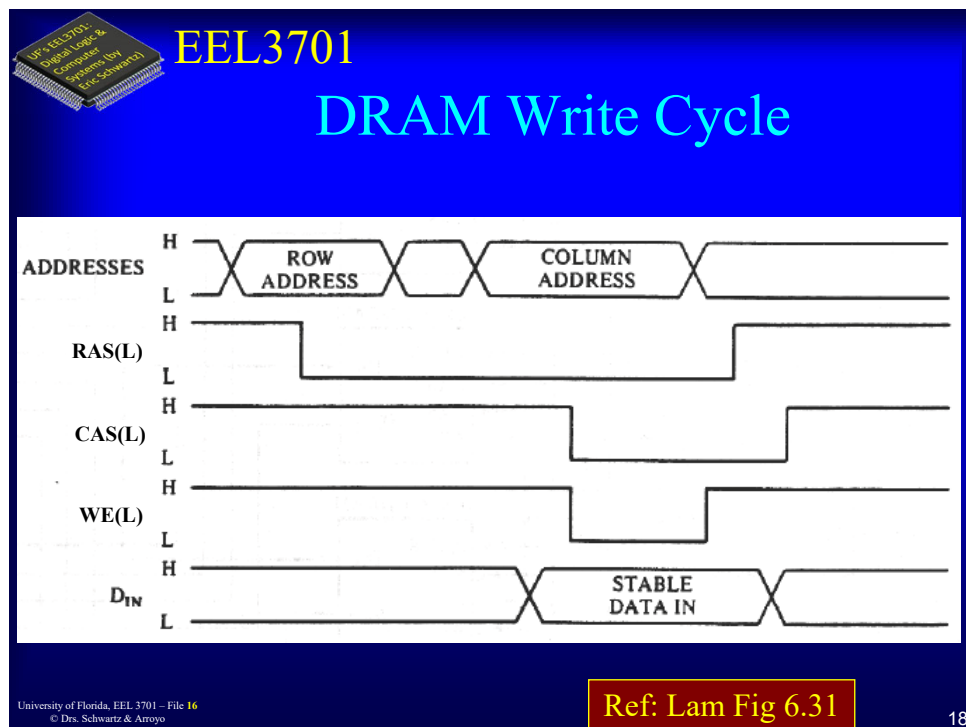
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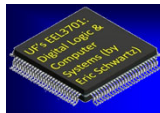
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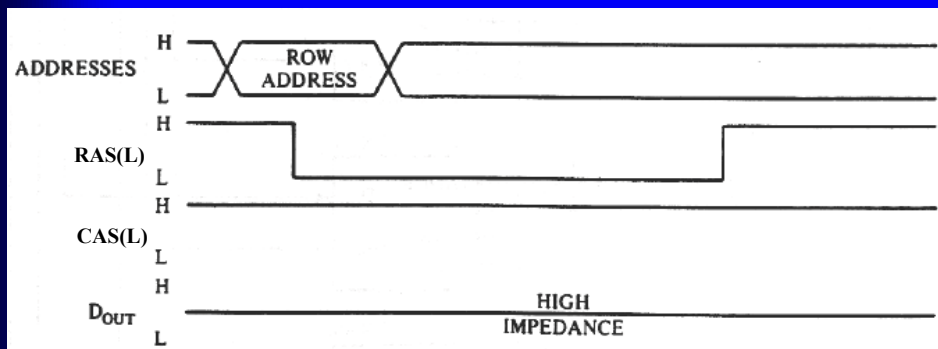


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DRAM RAS-Only Refresh Cycle

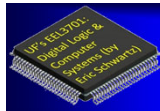


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Ref: Lam Fig 6.31

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Read Only Memory (ROM)

- It is “**non-volatile**” (no power required to hold the information).
- **ROM** (masked ROM) is manufactured with its content already supplied and is, therefore, “non- reversible.”
- **PROM** is “programmable” ROM, like PLA’s & PAL’s you “blow” fuses to program it. It retains data even after power is disconnected.
- **EPROM** (Erasable/Programmable ROM) is programmed with higher voltage pulses and is erasable by exposing the chip to ultraviolet light. (erase time: 5 ~ 15 minutes is typical); ex: 2764 (8kx8), 2708 (1kx8)
- **EEPROM** (Electrically Erasable/Programmable ROM) is electrically alterable via higher voltage pulses. Typical erase times are 1 ms per row (or bank) or per item. ex: 2864 (8kx8)
- **FLASH** EEPROM is electrically alterable. Newer than regular EEPROM. ex: 28F256 (32kx8)
- See http://mil.ufl.edu/3701/docs/umbc_8086_memory1.html

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EEL3701 ROM Model

- A “typical” 8k x 8 ROM:

- ROM is ideal for storing **non-changing software** such as the bootstrap and diagnostic software on PC's. (e.g., BIOS [basic I/O system] in PCs)

Function	CE	OE	D
Disable ROM	0	-	Hi-Z
Disable ROM	-	0	Hi-Z
Read	1	1	Out

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EEL3701 Example EPROM Operation

2716: 2k x 8 EPROM

Operation	CE/PRG	OE	Vpp	D ₇₋₀
Read	L	L	+5 V	Out
Standby	H	-	+5 V	High Z
Program	L → H	H	+25 V	In
Program Verify	L	L	+25 V	Out
Program Inhibit	L	H	+25 V	High Z

- Q₇₋₀ = D₇₋₀ = Data Bus
- A₁₀₋₀ = A₁₀₋₀ = Address Bus
- V_{ss} = GND
- /EP = CE/PRG
- V_{pp} = Program Supply
- G = OE = Output Enable

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Example EEPROM Operation

2864: 8k × 8 EEPROM

Operation	CE	OE	WE	D ₇₋₀
Read	L	L	H	Out
Write	L	H	L	In
Standby/Write Inhibit	H	-	-	High Z
Write Inhibit	-	-	H	
Write Inhibit	-	L	-	
Output Disable	-	H	-	High Z
Chip Erase	L	12V	L	High Z

2864 EEPROM

13 → A₁₂₋₀
 8 ↔ D₇₋₀
 CE
 OE
 WE
 Vcc +5V

• I/O7-0 = D₇₋₀ = Data Bus
 • A₁₂₋₀ = A₁₂₋₀ = Address Bus
 • NC = No Connection

H = +5V

See Software/Docs: "2864"

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BCD-to-7-segment Converter

Where

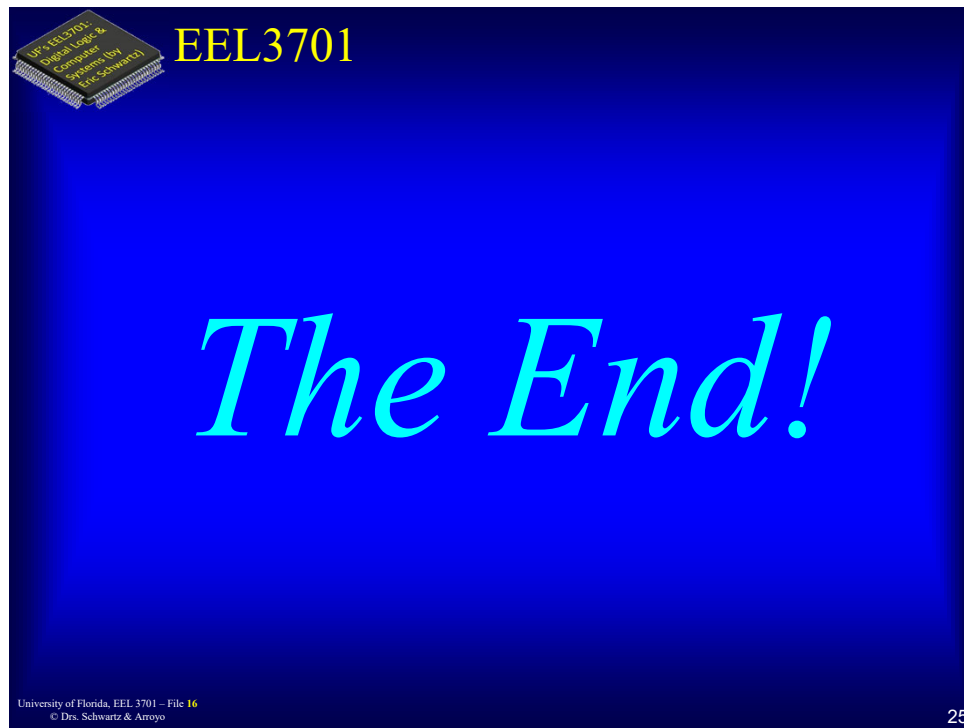
Z₆ = a
 Z₅ = b
 Z₄ = c
 Z₃ = d
 Z₂ = e
 Z₁ = f
 Z₀ = g

B ₃	B ₂	B ₁	B ₀	(a) Z ₆	(b) Z ₅	(c) Z ₄	(d) Z ₃	(e) Z ₂	(f) Z ₁	(g) Z ₀
0	0	0	0	1	1	1	1	1	1	0
0	0	0	1	0	1	1	0	0	0	0
0	0	1	0	1	1	0	1	1	0	1
0	0	1	1	1	1	1	1	0	0	1
0	1	0	0	0	1	1	0	0	1	1
0	1	0	1	1	0	1	1	0	1	1
0	1	1	0	1	0	1	1	1	1	1
0	1	1	1	1	1	1	0	0	0	0
1	0	0	0	1	1	1	1	1	1	1
1	0	0	1	1	1	1	1	0	1	1
1	0	1	0	0	0	0	0	0	0	0
1	0	1	1	0	0	0	0	0	0	0
1	1	0	0	0	0	0	0	0	0	0
1	1	0	1	0	0	0	0	0	0	0
1	1	1	0	0	0	0	0	0	0	0
1	1	1	1	0	0	0	0	0	0	0

Ref: Lam Fig 6.28

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